





SURFACE MOUNT SCHOTTKY BARRIER DIODE

Features

- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Leadless Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Bar
- Terminals: Finish NiPdAu Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 €
- Weight: 0.001 grams (Approximate)

X1-DFN1006-2





Top View

Bottom View

Ordering Information (Note 4)

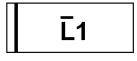
| Part Number | Case | Packaging |
|-------------|--------------|--------------------|
| BAT54LP-7 | X1-DFN1006-2 | 3,000/Tape & Reel |
| BAT54LP-7B | X1-DFN1006-2 | 10,000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information







Top View

Top View

Bar Denotes Cathode Side

L1 or L

1 = Product Type Marking Code
Bar Denotes Cathode Side



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | Symbol | Value | Unit |
|--|------------|---|-------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | | V _{RRM} V _R wm V _R | 30 | ٧ |
| Forward Continuous Current | | I _F | 200 | mA |
| Repetitive Peak Forward Current | | I _{FRM} | 300 | mA |
| Forward Surge Current | @ t < 1.0s | I _{FSM} | 600 | mA |

Thermal Characteristics

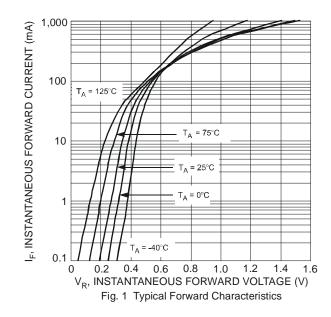
| Characteristic | Symbol | Value | Unit |
|--|-----------------------------------|-------------|------|
| Power Dissipation (Note 5) | P _D | 250 | mW |
| Thermal Resistance, Junction to Ambient Air (Note 5) | $R_{	hetaJA}$ | 400 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -65 to +125 | °C |

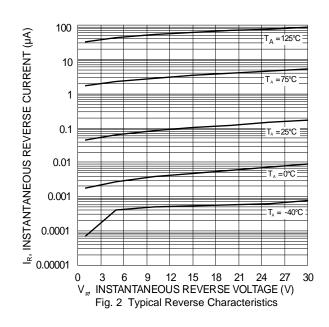
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|------------------------------------|-----------------|-----|-----|-----------------------------------|------|--|
| Reverse Breakdown Voltage (Note 6) | $V_{(BR)R}$ | 30 | _ | _ | V | $I_R = 100\mu A$ |
| Forward Voltage | VF | | _ | 240 320 400 500 1,000 | mV | I _F = 0.1mA I _F = 1mA I _F = 10mA I _F = 30mA I _F = 100mA |
| Reverse Leakage Current (Note 6) | I_R | | _ | 2.0 | μA | $V_R = 25V$ |
| Total Capacitance | Ст | | _ | 10 | pF | $V_R = 1.0V, f = 1.0MHz$ |
| Reverse Recovery Time | t _{RR} | | _ | 5.0 | ns | I_F = 10mA through I_R = 10mA to I_R = 1.0mA, R_L = 100 Ω |

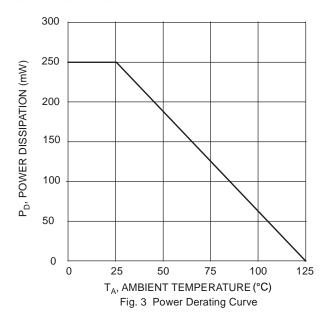
Notes:

- 5. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com/package-outlines.html.
- 6. Short duration pulse test used to minimize self-heating effect.





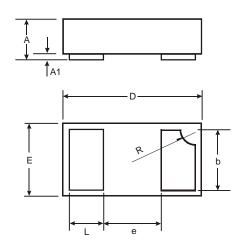




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1006-2

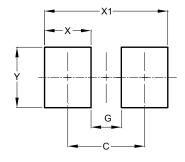


| X1-DFN1006-2 | | | | | |
|----------------------|------|-------|------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 0.47 | 0.53 | 0.50 | | |
| A1 | 0 | 0.05 | 0.03 | | |
| b | 0.45 | 0.55 | 0.50 | | |
| D | 0.95 | 1.075 | 1.00 | | |
| Е | 0.55 | 0.675 | 0.60 | | |
| е | - | - | 0.40 | | |
| L | 0.20 | 0.30 | 0.25 | | |
| R | 0.05 | 0.15 | 0.10 | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1006-2



| Dimensions | Value (in mm) | | |
|------------|------------------|--|--|
| С | 0.70 | | |
| G | 0.30 | | |
| Х | 0.40 | | |
| X1 | 1.10 | | |
| Υ | 0.70 | | |



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